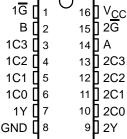
# CD54ACT153, CD74ACT153 DUAL 4-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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- Inputs Are TTL-Voltage Compatible
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
  - Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

# CD54ACT153...F PACKAGE CD74ACT153...E OR M PACKAGE (TOP VIEW) 1G 1 16 V<sub>CC</sub> B 12 15 12 G



#### description/ordering information

Each of these data selectors/multiplexers contains inverters and drivers to supply full binary decoding data selection to the AND-OR gates. Separate strobe  $(\overline{G})$  inputs are provided for each of the two 4-line sections.

#### **ORDERING INFORMATION**

TA	PACK	\GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74ACT153E	CD74ACT153E
5500 1- 40500	SOIC – M	Tube	CD74ACT153M	ACT153M
–55°C to 125°C	301C - W	Tape and reel	CD74ACT153M96	ACT 155IVI
	CDIP – F	Tube	CD54ACT153F3A	CD54ACT153F3A

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **FUNCTION TABLE**

	INPUTS											
SELI	ЕСТ‡		DA	TΑ	G	OUTPUT Y						
В	Α	C0	C1	C2	C3	G	·					
Х	Х	Х	Χ	Χ	Х	Н	L					
L	L	L	Χ	X	X	L	L					
L	L	Н	Χ	X	X	L	Н					
L	Н	Х	L	Χ	Χ	L	L					
L	Н	Х	Н	X	X	L	Н					
Н	L	Х	Χ	L	X	L	L					
Н	L	Х	Χ	Н	X	L	Н					
Н	Н	Х	Χ	Χ	L	L	L					
Н	Н	Х	Χ	Χ	Н	L	Н					

<sup>‡</sup> Select inputs A and B are common to both sections.

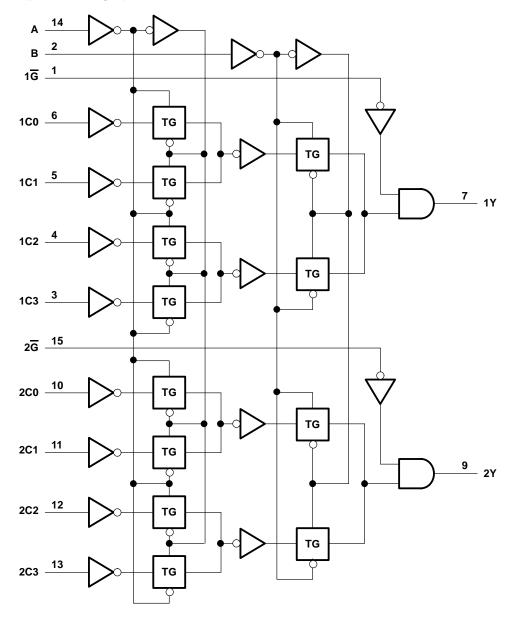


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## logic diagram (positive logic)



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#### absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): E package	67°C/W
M package	73°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

#### recommended operating conditions (see Note 3)

		T <sub>A</sub> = 2	25°C	–55°C to 125°C		–40°C to 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		8.0		0.8	V
٧ <sub>I</sub>	Input voltage	0	VCC	0	VCC	0	VCC	V
٧o	Output voltage	0	VCC	0	VCC	0	Vcc	V
IOH	High-level output current		-24		-24		-24	mA
l <sub>OL</sub>	Low-level output current		24		24		24	mA
Δt/Δν	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# CD54ACT153, CD74ACT153 DUAL 4-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST COM	Vcc	T <sub>A</sub> = 1	T <sub>A</sub> = 25°C		C to °C	–40°C to 85°C		UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX		
		I <sub>OH</sub> = -50 μA	4.5 V	4.4		4.4		4.4			
V	\\. = \\ or \\	$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8		٧	
VOH	$V_I = V_{IH}$ or $V_{IL}$	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85				v	
		I <sub>OH</sub> = -75 mA†	5.5 V					3.85			
	VI = VIH or VIL	I <sub>OL</sub> = 50 μA	4.5 V		0.1		0.1		0.1		
V		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44	٧	
VOL		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65			V	
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65		
lį	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μΑ	
Icc	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μΑ	
Δl <sub>CC</sub> ‡	$V_{I} = V_{CC} - 2.1 \text{ V}$		4.5 V to 5.5 V		2.4		3		2.8	mA	
Ci					10		10		10	pF	

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C. ‡ Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

#### **ACT INPUT LOAD TABLE**

INPUT	UNIT LOAD
A or B	1
С	1
G	0.47

Unit Load is  $\Delta I_{CC}$  limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

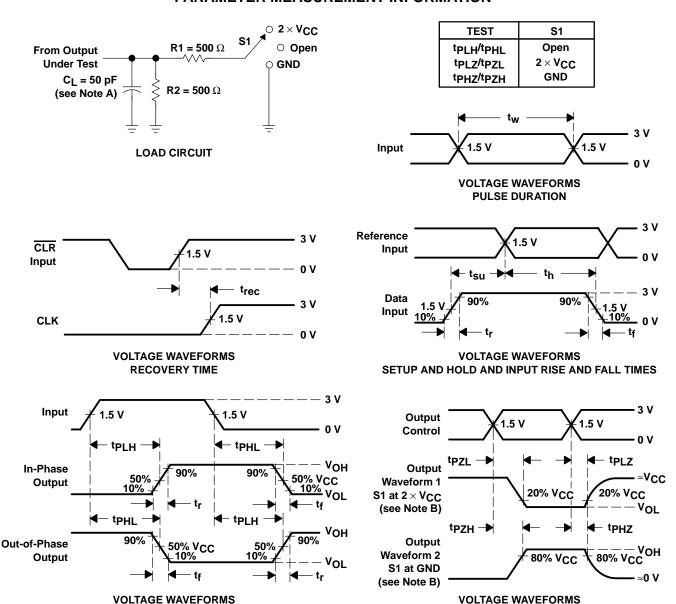
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°( 125		–40°C to 85°C		UNIT
	(INFOT)	(001701)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	<b>v</b>	5.5	22	5.7	20	ns
<sup>t</sup> PHL		1	5.5	22	5.7	20	115
<sup>t</sup> PLH	Arrico	<b>~</b>	4.5	18	4.6	16.4	ne
<sup>t</sup> PHL	Any C	'	4.5	18	4.6	16.4	ns
<sup>t</sup> PLH	G	~	3.2	12.6	3.2	11.5	no
<sup>t</sup> PHL	9	r	3.2	12.6	3.2	11.5	ns

### operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	93	pF



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and test-fixture capacitance.

PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 3 \ ns$ ,  $t_f = 3 \ ns$ . Phase relationships between waveforms are arbitrary.

**OUTPUT ENABLE AND DISABLE TIMES** 

- D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tpz and tpzH are the same as ten.
- H.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD54ACT153F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54ACT153F3A	Samples
CD74ACT153E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT153E	Samples
CD74ACT153M	LIFEBUY	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT153M	
CD74ACT153M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT153M	Samples
CD74ACT153NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT153M	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

## **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF CD54ACT153, CD74ACT153:

Catalog: CD74ACT153

Military: CD54ACT153

NOTE: Qualified Version Definitions:

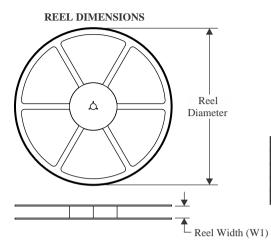
Catalog - TI's standard catalog product

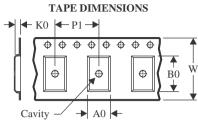
• Military - QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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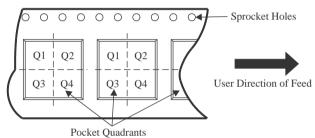
#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

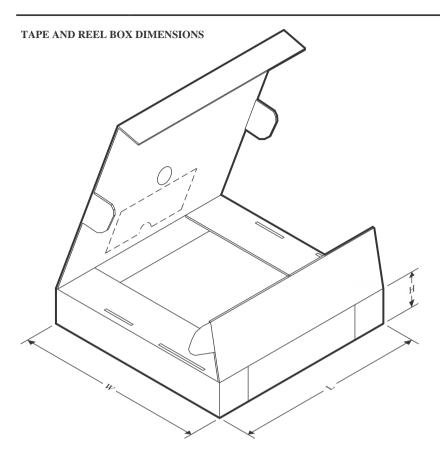


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT153M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT153NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

# **PACKAGE MATERIALS INFORMATION**

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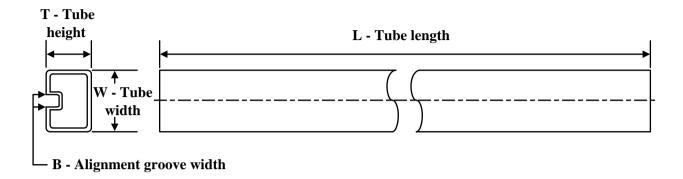
#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT153M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74ACT153NSR	SO	NS	16	2000	356.0	356.0	35.0

# **PACKAGE MATERIALS INFORMATION**

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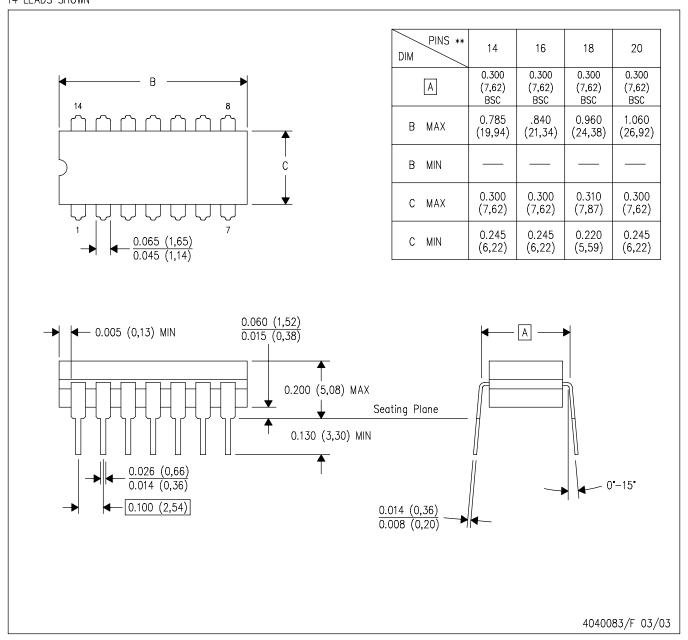
#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74ACT153E	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT153E	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT153M	D	SOIC	16	40	507	8	3940	4.32

## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

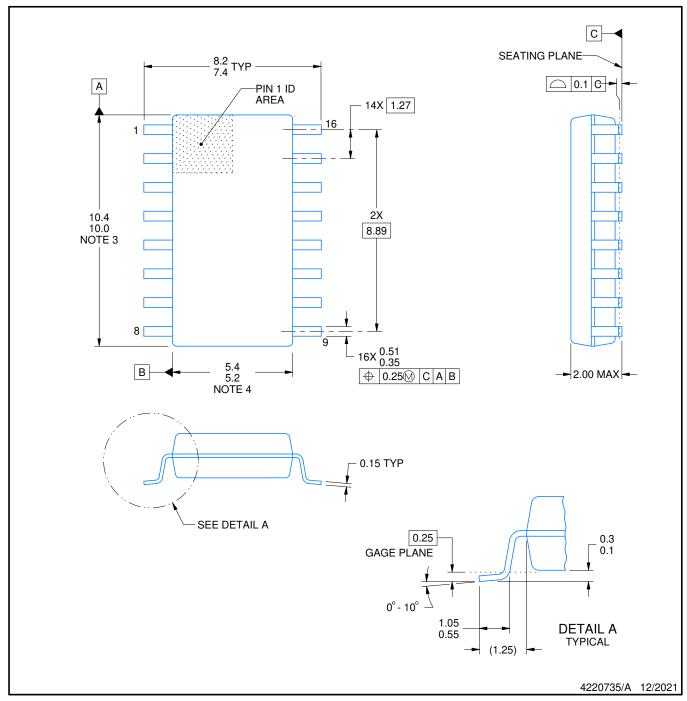


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



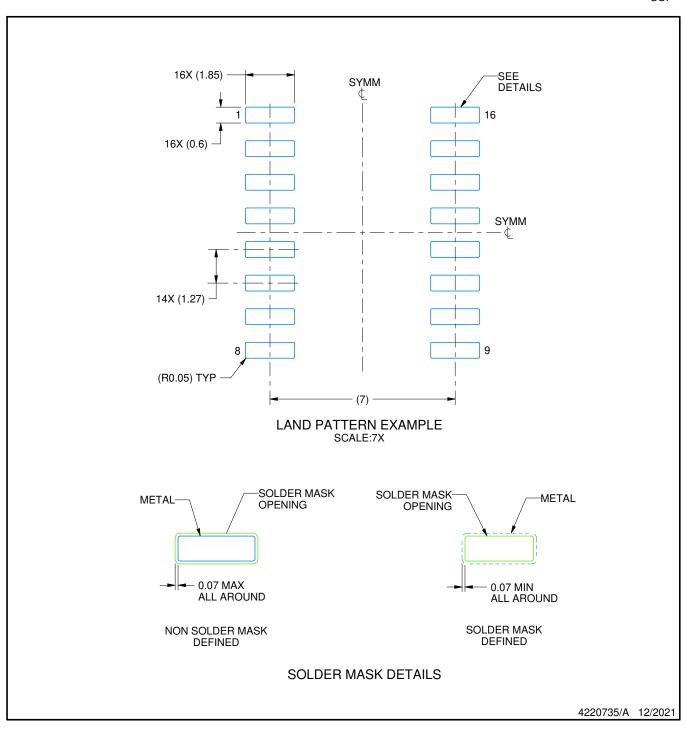
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



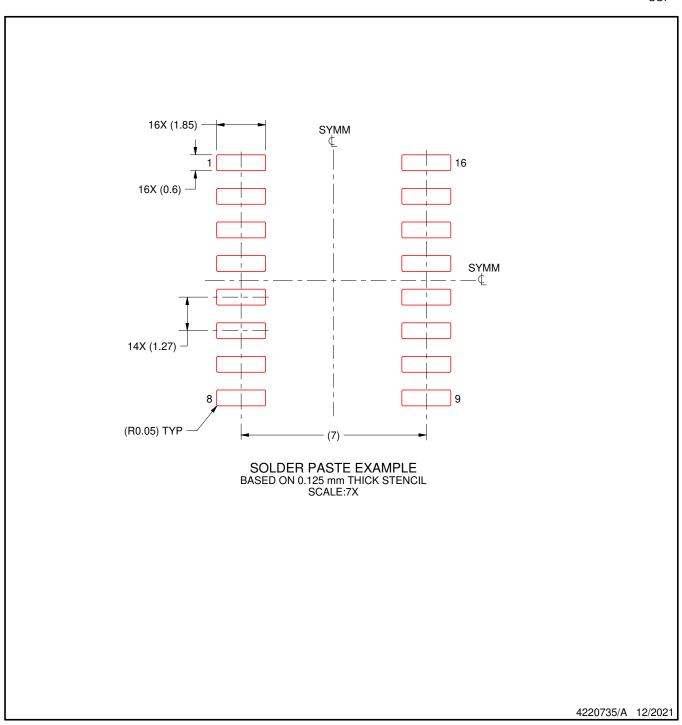
#### NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOP



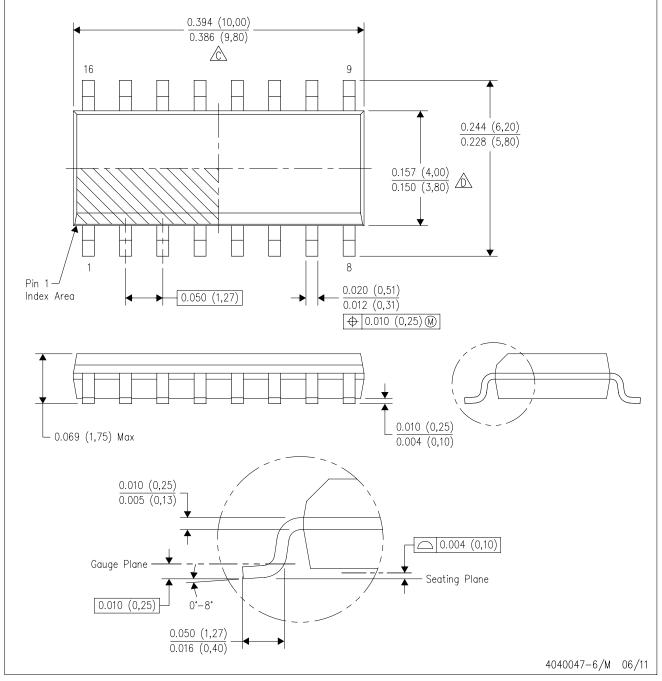
#### NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



# D (R-PDS0-G16)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



#### **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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